



Material Content Data Sheet



Sales Product Name		IPS060N03L G		Issued		29. August 2013		
MA#		MA000707214						
Package		PG-TO251-3-311		Weight*		333.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.985	0.30	0.30	2950	2950
leadframe	non noble metal	iron	7439-89-6	0.176	0.05		528	
	inorganic material	phosphorus	7723-14-0	0.053	0.02		158	
	non noble metal	copper	7440-50-8	175.989	52.71	52.78	527245	527931
wire	non noble metal	aluminium	7429-90-5	2.156	0.65	0.65	6459	6459
encapsulation	organic material	carbon black	1333-86-4	0.328	0.10		982	
	plastics	epoxy resin	-	19.794	5.93		59302	
	inorganic material	silicondioxide	60676-86-0	128.932	38.63	44.66	386267	446551
leadfinish	non noble metal	tin	7440-31-5	3.002	0.90	0.90	8992	8992
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11	
	non noble metal	nickel	7440-02-0	1.555	0.47	0.47	4657	4668
solder	noble metal	silver	7440-22-4	0.020	0.01		61	
	non noble metal	tin	7440-31-5	0.016	0.00		49	
	non noble metal	lead	7439-92-1	0.781	0.23	0.24	2339	2449
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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